

Product End-of-Life Disassembly Instructions
Product Category: **Networking**
Marketing Name / Model
[List multiple models if applicable.]

JL728A Aruba 6200F 48G CL4 4SFP+ 740W Swch

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torque Driver (Standard)	
Torque Bit	T10
Torque Bit	T25
Torque Bit	M4 Philip Head
Cutter	
Soldering Station	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove PULL OUT
2. Unscrew and remove – M5 SCREW at 1 Location
3. Unscrew and remove – M3 SCREW at 14 Locations and CHASSIS COVER
4. Remove - INSULATOR from CHASSIS COVER
5. Cut and remove – CABLE TIE at 3 Locations
6. Unplug - AC connector from POWER SUPPLY
7. Unplug - FAN connector from POWER SUPPLY
8. Unplug - POWER SUPPLY connector from PCBA, MAIN BOARD
9. Unplug - FAN connector from PCBA, MAIN BOARD
10. Unplug – FFC CABLE from PCBA, LED BOARD
11. Remove – POWER SUPPLY CABLE from SADDLE CABLE
12. Remove – BUSHING CABLE from CHASSIS
13. Unscrew and remove – M3 SCREW at 5 Locations and POWER SUPPLY
14. Unplug – FFC CABLE from PCBA, MAIN BOARD
15. Unscrew and remove – M3 SCREW at 2 Locations
16. Remove PCBA, LED BOARD
17. Remove PUSHBUTTON
18. Unscrew and remove M3 SCREW at 2 Locations and SHIELD PSU CABLE
19. Unscrew and remove M4 SCREW at 1 Location
20. Unscrew and remove M4 SCREW at 6 Locations and FAN
21. Unplug and remove - AC socket from CHASSIS
22. Remove – COIN BATTERY from BATTERY SOCKET
23. Unscrew and remove SC - M3 SCREW at 11 Locations and PCBA, MAIN BOARD
24. Remove INSULATOR from CHASSIS
25. Remove INSULATOR from CHASSIS
26. Remove – FRONT OVERLAY from CHASSIS

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27. Desolder and Remove – Capacitor from PCBA, POWER SUPPLY
28. Remove - SADDLE CABLE from SHIELD PSU CABLE

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).















